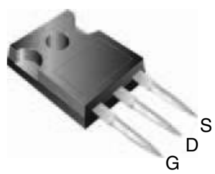
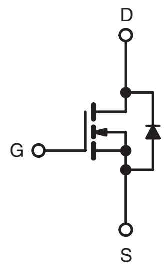
Power MOSFET

PRODUCT SUMMARY		
V_{DS} (V)	600	
$R_{DS(on)}$ (Ω)	V_{GS} = 10 V	0.24
Q_g (Max.) (nC)	150	
Q_{gs} (nC)	45	
Q_{gd} (nC)	76	
Configuration	Single	

TO-247





N-Channel MOSFET

FEATURES

- Hard Switching Primary or PFS Switch
- Low Gate Charge Q_g Results in Simple Drive Requirement
- Improved Gate, Avalanche and Dynamic dV/dt Ruggedness
- Fully Characterized Capacitance and Avalanche Voltage and Current
- Enhanced Body Diode dV/dt Capability
- Lead (Pb)-free Available

Pb Available
RoHS*
COMPLIANT

BENEFITS

- Switch Mode Power Supply (SMPS)
- Uninterruptible Power Supply
- High Speed Power Switching
- Motor Drive

ORDERING INFORMATION	
Package	TO-247
Lead (Pb)-free	IRFP22N60KPbF
	SiHFP22N60K-E3
SnPb	IRFP22N60K
	SiHFP22N60K

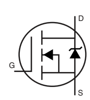
ABSOLUTE MAXIMUM RATINGS T_C = 25 °C, unless otherwise noted

PARAMETER			SYMBOL	LIMIT	UNIT
Drain-Source Voltage			V_{DS}	600	V
Gate-Source Voltage			V_{GS}	± 30	
Continuous Drain Current	V_{GS} at 10 V	T_C = 25 °C	I_D	22	A
		T_C = 100 °C		14	
Pulsed Drain Current[a]			I_{DM}	88	
Linear Derating Factor				2.9	W/°C
Single Pulse Avalanche Energy[b]			E_{AS}	380	mJ
Repetitive Avalanche Current[a]			I_{AR}	22	A
Repetitive Avalanche Energy[a]			E_{AR}	37	mJ
Maximum Power Dissipation	T_C = 25 °C		P_D	370	W
Peak Diode Recovery dV/dt[c]			dV/dt	15	V/ns
Operating Junction and Storage Temperature Range			T_J, T_{stg}	- 55 to + 150	°C
Soldering Recommendations (Peak Temperature)	for 10 s			300[d]	

Notes
a. Repetitive rating; pulse width limited by maximum junction temperature (see fig. 11).
b. Starting T_J = 25 °C, L = 1.5 mH, R_G = 25 Ω, I_{AS} = 22 A (see fig. 12).
c. $I_{SD} \le 22$ A, dI/dt ≤ 360 A/µs, $V_{DD} \le V_{DS}$, $T_J \le 150$ °C.
d. 1.6 mm from case.

* Pb containing terminations are not RoHS compliant, exemptions may apply

THERMAL RESISTANCE RATINGS				
PARAMETER	**SYMBOL**	**TYP.**	**MAX.**	**UNIT**
Maximum Junction-to-Ambient	R_{thJA}	-	40	°C/W
Case-to-Sink, Flat, Greased Surface	R_{thCS}	0.24	-	
Maximum Junction-to-Case (Drain)	R_{thJC}	-	0.34	

SPECIFICATIONS T_J = 25 °C, unless otherwise noted						
PARAMETER	**SYMBOL**	**TEST CONDITIONS**	**MIN.**	**TYP.**	**MAX.**	**UNIT**
Static						
Drain-Source Breakdown Voltage	V_{DS}	V_{GS} = 0 V, I_D = 250 µA	600	-	-	V
V_{DS} Temperature Coefficient	$\Delta V_{DS}/T_J$	Reference to 25 °C, I_D = 1 mA[d]	-	0.30	-	V/°C
Gate-Source Threshold Voltage	$V_{GS(th)}$	V_{DS} = V_{GS}, I_D = 250 µA	3.0	-	5.0	V
Gate-Source Leakage	I_{GSS}	V_{GS} = ± 30 V	-	-	± 100	nA
Zero Gate Voltage Drain Current	I_{DSS}	V_{DS} = 600 V, V_{GS} = 0 V	-	-	50	µA
		V_{DS} = 480 V, V_{GS} = 0 V, T_J = 125 °C	-	-	250	
Drain-Source On-State Resistance	$R_{DS(on)}$	V_{GS} = 10 V; I_D = 13 A[b]	-	0.240	0.280	Ω
Forward Transconductance	g_{fs}	V_{DS} = 50 V, I_D = 13 A[b]	11	-	-	S
Dynamic						
Input Capacitance	C_{iss}	V_{GS} = 0 V, V_{DS} = 25 V, f = 1.0 MHz, see fig. 5	-	3570	-	pF
Output Capacitance	C_{oss}		-	350	-	
Reverse Transfer Capacitance	C_{rss}		-	36	-	
Output Capacitance	C_{oss}	V_{GS} = 0 V; V_{DS} = 1.0 V , f = 1.0 MHz	-	4710	-	
		V_{GS} = 0 V; V_{DS} = 480 V , f = 1.0 MHz	-	92	-	
Effective Output Capacitance	C_{oss} eff.	V_{GS} = 0 V; V_{DS} = 0 V to 480 V	-	180	-	
Total Gate Charge	Q_g	V_{GS} = 10 V; I_D = 22 A, V_{DS} = 480 V see fig. 6 and 13[b]	-	-	150	nC
Gate-Source Charge	Q_{gs}		-	-	45	
Gate-Drain Charge	Q_{gd}		-	-	76	
Turn-On Delay Time	$t_{d(on)}$	V_{DD} = 300 V, I_D = 22 A, R_G = 6.2, V_{GS} = 10 V, see fig. 10[b]	-	26	-	ns
Rise Time	t_r		-	99	-	
Turn-Off Delay Time	$t_{d(off)}$		-	48	-	
Fall Time	t_f		-	37	-	
Drain-Source Body Diode Characteristics						
Continuous Source-Drain Diode Current	I_S	MOSFET symbol showing the integral reverse p - n junction diode 	-	-	22	A
Pulsed Diode Forward Current[a]	I_{SM}		-	-	88	
Body Diode Voltage	V_{SD}	T_J = 25 °C, I_S = 22 A, V_{GS} = 0 V[b]	-	-	1.5	V
Body Diode Reverse Recovery Time	t_{rr}	T_J = 25 °C; I_F = 22 A, dI/dt = 100 A/µs[b]	-	590	890	ns
		T_J = 125 °C	-	670	1010	
Body Diode Reverse Recovery Charge	Q_{rr}	T_J = 25 °C	-	7.2	11	µC
		T_J =1 25 °C	-	8.5	13	
Reverse Recovery Current	I_{RRM}	T_J = 25 °C	-	26	39	
Forward Turn-On Time	t_{on}	Intrinsic turn-on time is negligible (turn-on is dominated by L_S and L_D)				

Notes
a. Repetitive rating; pulse width limited by maximum junction temperature (see fig. 11).
b. Pulse width ≤ 300 µs; duty cycle ≤ 2 %.
c. C_{oss} eff. is a fixed capacitance that gives the same charging time as C_{oss} while V_{DS} is rising from 0 to 80 % V_{DS}.

TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted

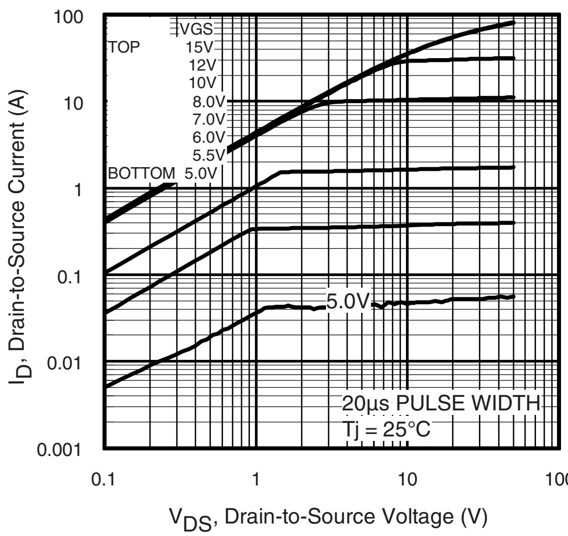


Fig. 1 - Typical Output Characteristics

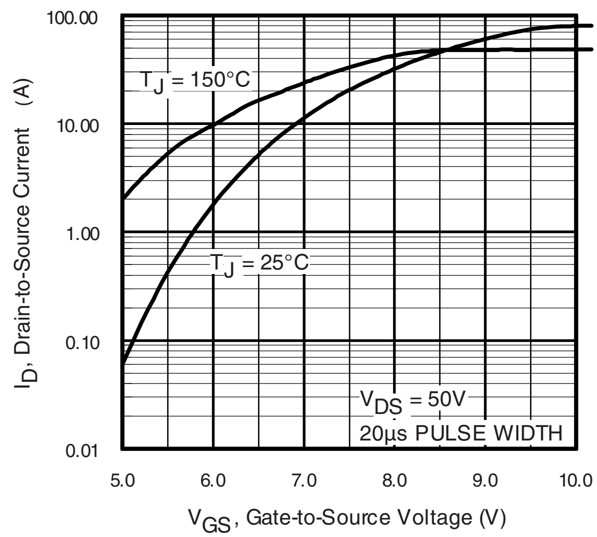


Fig. 3 - Typical Transfer Characteristics

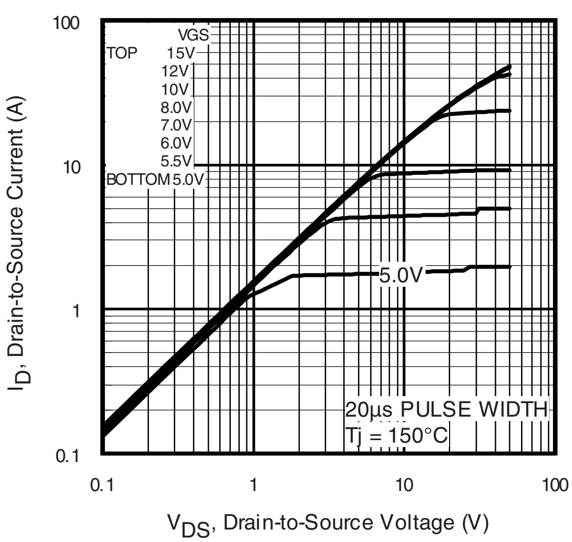


Fig. 2 - Typical Output Characteristics

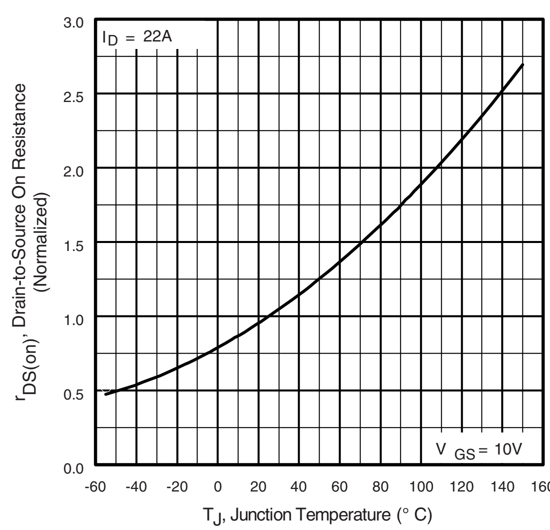


Fig. 4 - Normalized On-Resistance vs. Temperature

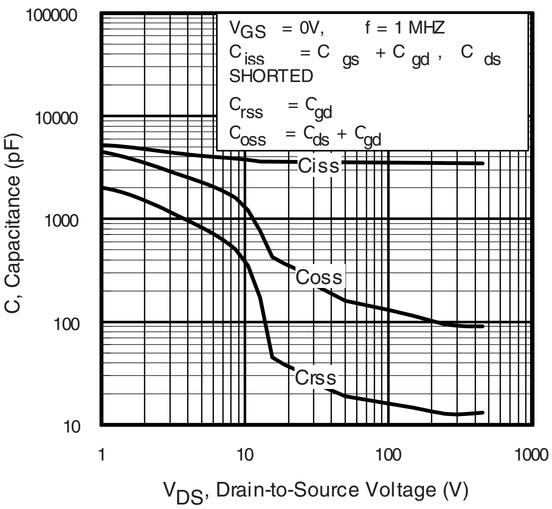


Fig. 5 - Typical Capacitance vs. Drain-to-Source Voltage

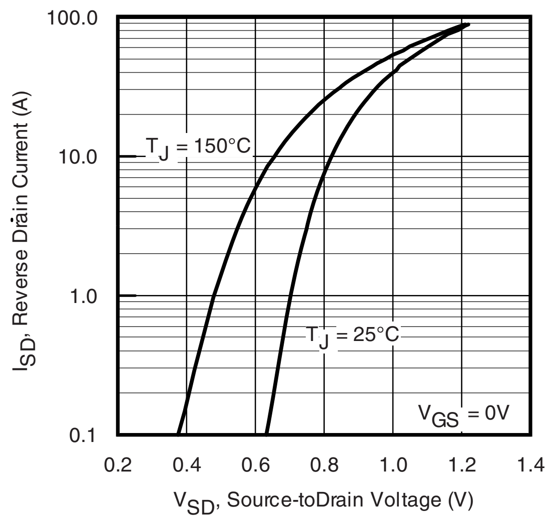


Fig. 7 - Typical Source-Drain Diode Forward Voltage

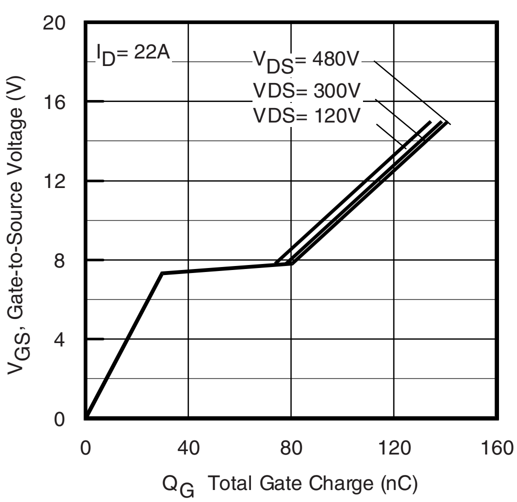


Fig. 6 - Typical Gate Charge vs. Gate-to-Source Voltage

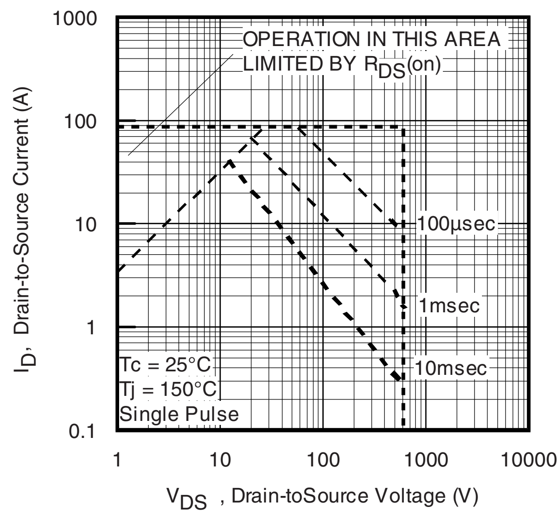


Fig. 8 - Maximum Safe Operating Area

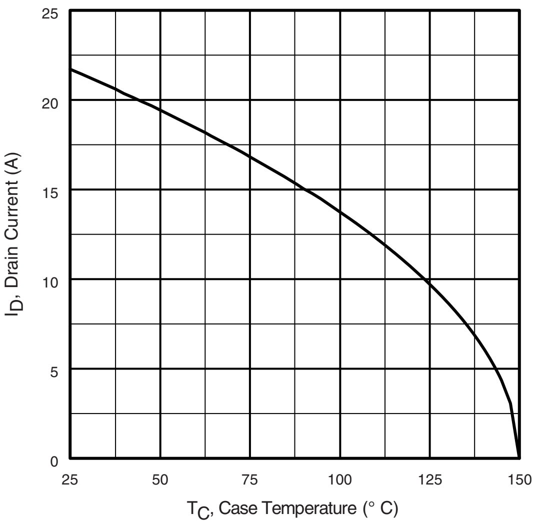


Fig. 9 - Maximum Drain Current vs. Case Temperature

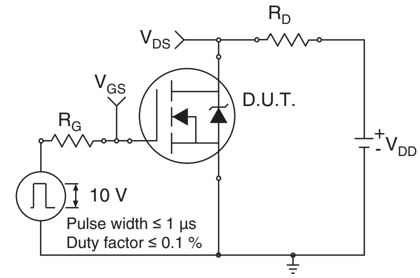


Fig. 10a - Switching Time Test Circuit

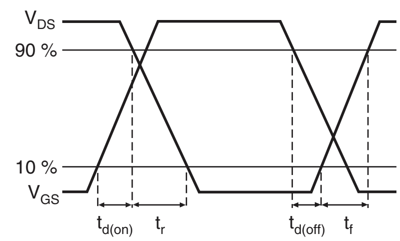


Fig. 10b - Switching Time Waveforms

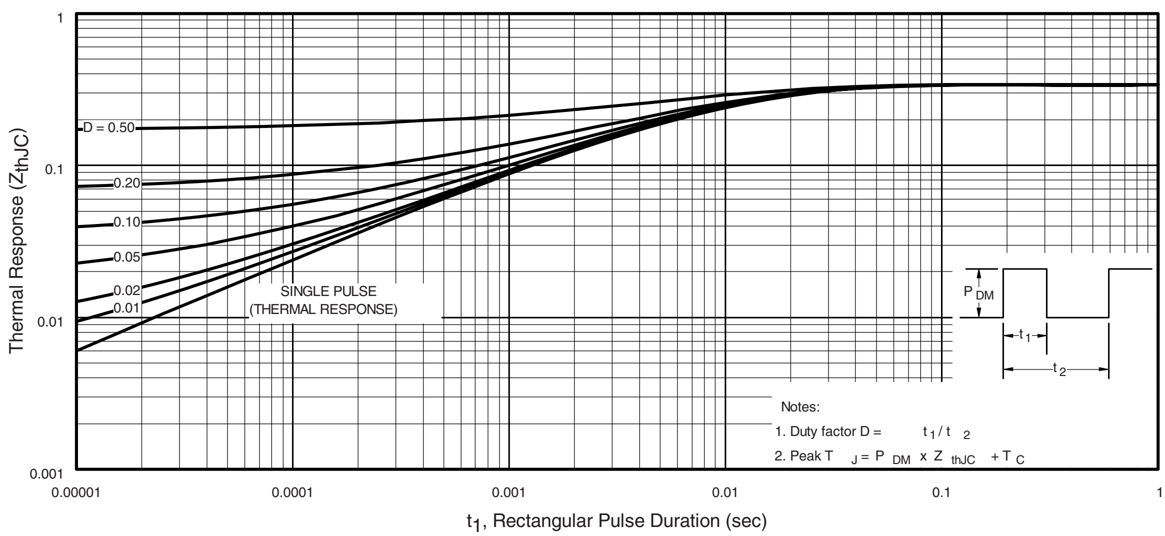


Fig. 11 - Maximum Effective Transient Thermal Impedance, Junction-to-Case

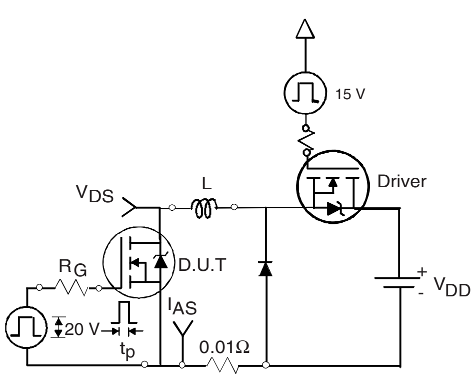


Fig. 12a - Unclamped Inductive Test Circuit

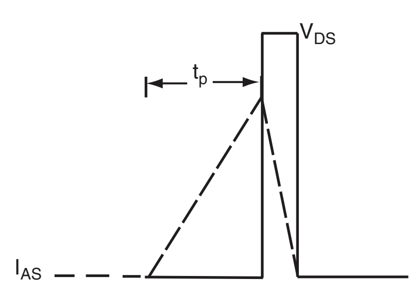


Fig. 12b - Unclamped Inductive Waveforms

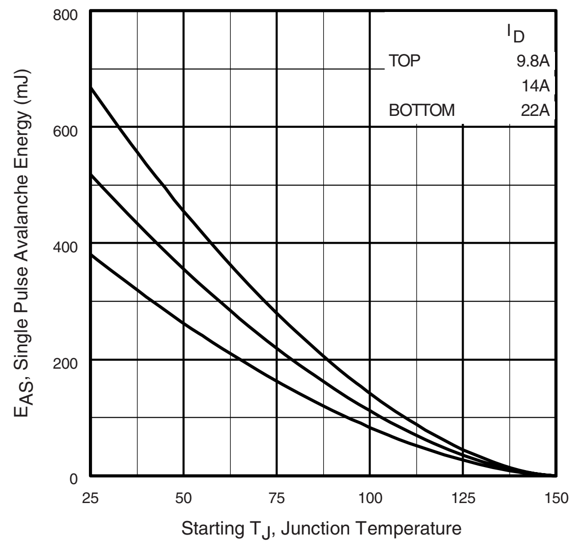


Fig. 12c - Maximum Avalanche Energy vs. Drain Current

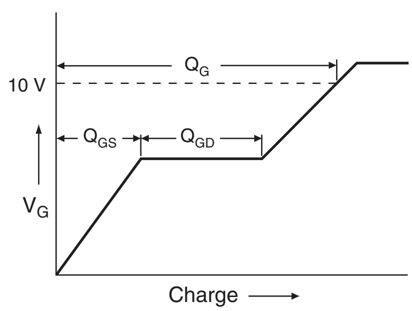


Fig. 13a - Basic Gate Charge Waveform

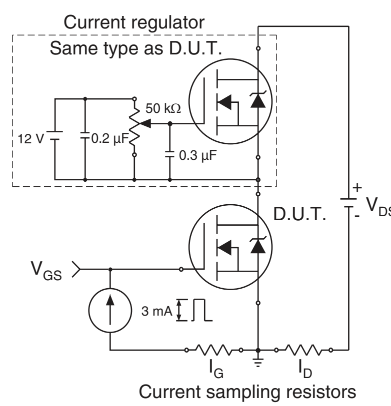
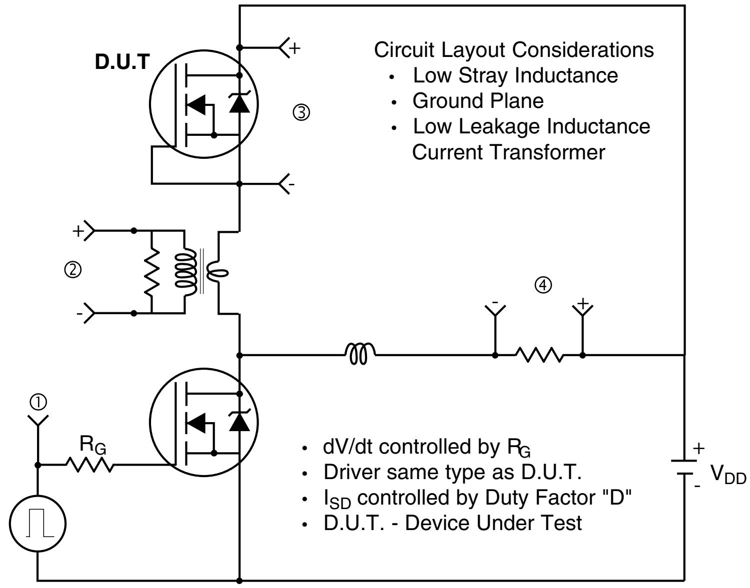
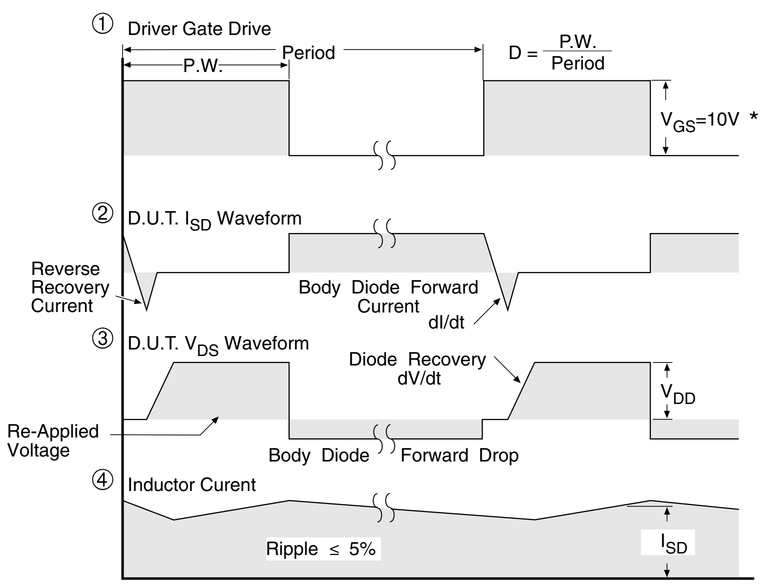


Fig. 13b - Gate Charge Test Circuit

Peak Diode Recovery dV/dt Test Circuit





* V_{GS} = 5V for Logic Level Devices

Fig. 14 - For N-Channel

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